DDC MULTIPLEXER HARDWARE:

DDC MULTIPLEXER SOFTWARE:
FEATURES:

- Carries a FC475 DDC Testboard or a CSP1200-220 Testboard with up to 24 dies with two daisy chains per die.
- Fast visualization of short cuts or broken connections with LED matrix
- Allows 6 differential measurements with up to 4 kelvin probe measurements per die
- On board high accuracy differential amplifier for small contact resistances
- Automated measurement, analysis and protocling with the DDC Multiplexer Software
- Easy measurement of short cuts between adjacent contacts

TECHNICAL INFORMATION:

available testboards
1. FC475 DDC Testboard for flip chip or wire bonding
2. CSP1200-220 Testboard for flip chip in different die geometries

automated measurements
1. Up to 4 single contact resistances with kelvin probe measurements per die
2. Total resistance of both daisy chains including all contacts
3. Short cuts between adjacent contacts

full measurement time
10 seconds

expected accuracy
(with NI 9205)
- 5mΩ - 15mΩ: ±10%
- 15mΩ - 50mΩ: ±5%
- 50mΩ - 100mΩ: ±2,5%
- > 100mΩ : ±1%

external hardware
National Instruments cRIO-Chassis with NI 9205 Analog Input Module

measurement protocol
Including
- Date and time
- Measurement settings
  - Testchip and mounting
  - Thresholds for resistances
- Measurement results
- Overview image

contact
Fraunhofer Institut für Siliziumtechnologie
Fraunhoferstraße 1; D-25524 Itzehoe
Internet: http://www.isit.fraunhofer.de

Dr.-Ing. Dipl. Phys. Dirk Kähler
Phone +49 (0) 48 21 / 17 – 46 04
Fax +49 (0) 48 21 / 17 – 42 50
Email: dirk.kaehler@isit.fraunhofer.de

Dr.-Ing. Wolfgang Reinert
Phone +49 (0) 48 21 / 17 – 42 16
Fax +49 (0) 48 21 / 17 – 42 50
Email: wolfgang.reinert@isit.fraunhofer.de

* Specifications subject to change without notice.
* All specified dimensions are approximate.